

SEMI G57-0302 (Reapproved 1015) GUIDE FOR STANDARDIZATION OF LEADFRAME TERMINOLOGY

This Standard was technically approved by the Assembly & Packaging Global Technical Committee. This edition was approved for publication by the global Audits and Reviews Subcommittee on July 6, 2015. Available at www.semiviews.org and www.semi.org in October 2015; originally published in 1993; previously published March 2002.

NOTICE: This Standard or Safety Guideline has an Inactive Status because the conditions to maintain Current Status have not been met. Inactive Standards or Safety Guidelines are available from SEMI and continue to be valid for use.

NOTICE: This Document was reapproved with minor editorial changes.

1 Purpose

1.1 This Guide defines standard terminologies for all the features of leadframes used in the production of semiconductor circuits.

1.2 *Significance* — Use of this Guide in communications between customers and vendors can reduce the errors caused by the current use of different nomenclatures for the same feature of a leadframe.

Table 1 Nomenclature for Figures

1	Die Pad
2	Die Pad Support
3	Lead Lock
4	Anchor Hole
5	Inner Lead
6	Outer Lead
7	Standard Pilot Hole
8	Pilot Hole
9	Top Rail Standard Pilot Hole Side
10	Bottom Rail
11	Lead Cut-off Notch
12	Dam Bar
13	Lead Shoulder
14	Mold Dam
15	Bumper Support Cut-off Notch
16	Lead Lock Groove
17	Mold Line
18	Expansion Slot
19	Down Set
20	Die Pad Dimple
21	Side Rail
22	Strip Cut-off Line
23	Coined Area
24	Degate Hole

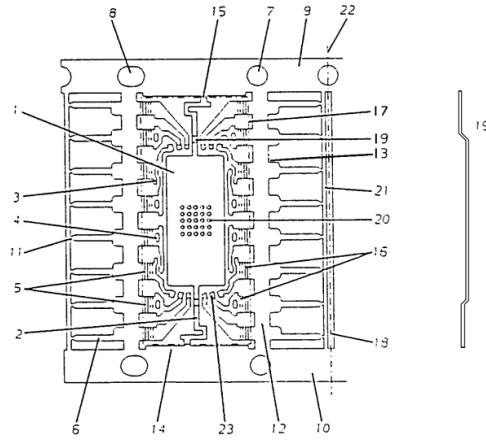


Figure 1

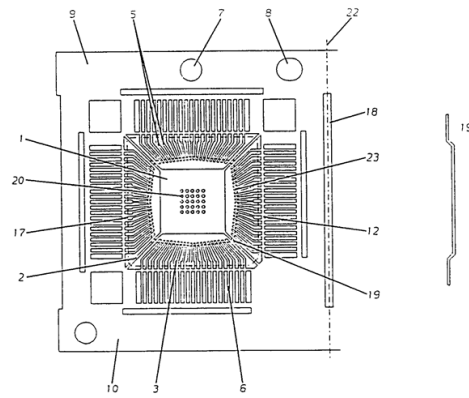


Figure 2

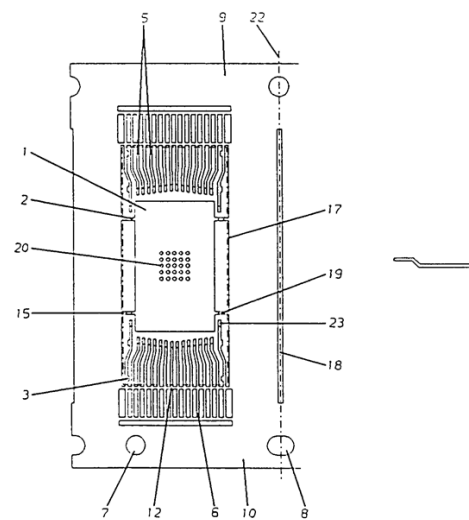


Figure 3